



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB039N10N3 G		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001263090						
<b>Package</b>		PG-TO263-7-3		<b>Weight*</b>		1526.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.861	0.58	0.58	5804	5804
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		526	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	copper	7440-50-8	801.714	52.50	52.57	525103	525787
wire	non noble metal	aluminium	7429-90-5	11.518	0.75	0.75	7544	7544
encapsulation	organic material	carbon black	1333-86-4	8.679	0.57		5685	
	plastics	epoxy resin	-	95.471	6.25		62531	
	inorganic material	silicondioxide	60676-86-0	474.463	31.08	37.90	310761	378977
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8067	8067
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	525102	176
solder	noble metal	silver	7440-22-4	0.152	0.01		100	
	non noble metal	tin	7440-31-5	0.122	0.01		80	
	non noble metal	lead	7439-92-1	5.815	0.38	0.40	3809	3989
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		70	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.96	6.97	69565	69656
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com